

Material Composition Specification

DIP Case



Device average mass 327 mg
 Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	1.38%	4.52	Si	7440-21-3	1.38%	4.52	13,830
leadframe	copper	35.53%	116.12	Cu	7440-50-8	35.53%	116.12	355,302
die attach	high temperature solder paste	3.0%	9.81	Pb	7439-92-1	2.77%	9.07	27,736
				Sn	7440-31-5	0.15%	0.49	1,499
				Ag	7440-22-4	0.07%	0.25	750
encapsulation*	EMC	59.76%	195.3	silica	7631-86-9	40.63%	132.8	406,329
				epoxy resin	29690-82-2	11.95%	39.07	119,514
				phenol resin	9003-35-4	5.98%	19.53	59,757
				Sb ₂ O ₃	1309-64-4	0.6%	1.95	5,975
				Br	7726-95-6	0.6%	1.95	5,975
	EMC GREEN	59.76%	195.3	silica (fused)	60676-86-0	46.01%	150.38	460,118
				epoxy resin	29690-82-2	5.98%	19.53	59,753
				phenol resin	9003-35-4	5.8%	18.94	57,963
				carbon black	1333-86-4	0.18%	0.59	1,792
				metal hydroxide	1309-42-8	1.79%	5.86	17,924
plating**	tin/lead process	0.33%	1.09	Sn	7440-31-5	0.27%	0.87	2,665
				Pb	7439-92-1	0.07%	0.22	667
	100% tin process	0.33%	1.09	Sn	7440-31-5	0.33%	1.09	3,332

*EMC GREEN molding compound is Halogen-Free.

**For Lead Free plating, add suffix "LEAD FREE" to part number.

For Tin/Lead plating, add suffix "TIN/LEAD" to part number.

No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R2 (3-June 2011)